

FNK N-Channel Enhancement Mode Power MOSFET

Description

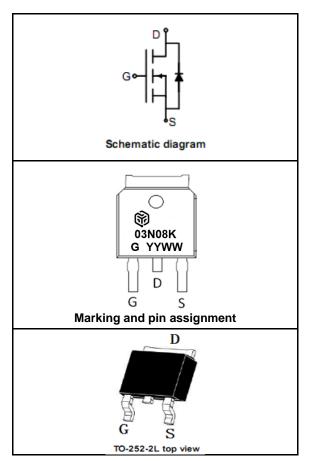
The FNK03N045K uses advanced trench technology and provide excellent $R_{\text{DS(ON)}}$ with low gate charge, it can be used in a wide variety of applications.

General Features

- $V_{DS} = 30V, I_{D} = 80$ A $R_{DS(ON)} < 8.0 mΩ$ @ $V_{GS} = 10V$ $R_{DS(ON)} < 14 mΩ$ @ $V_{GS} = 4.5V$
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high EAS
- Excellent package for good heat dissipation

Application

- Power switching application
- Hard switched and High frequency circuits
- Uninterruptible power supply



PACKAGE MARKING AND ORDERING INFORMATION

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
03N045K	FNK03N045K	TO -252			

ABSOLUTE MAXIMUM RATINGS(TA=25°C unless otherwise noted)

·		,	
Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _G s	±20	V
Proin Current Continuous & Current Bulead (Note 1)	I _D (25℃)	80	А
Drain Current-Continuous@ Current-Pulsed (Note 1)	I _{DM}	320	А
Maximum Power Dissipation	P _D	108	W
Single pulse avalanche energy(Note 5)	EAS	30	mJ

www.fnk-tech.com Page 1 V1.1



FNK03N08K

Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	$^{\circ}\! \mathbb{C}$
--	------------------	------------	-------------------------

THERMAL CHARACTERISTICS

ELECTRICAL CHARACTERISTICS (TA=25°Cunless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	30			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V			1	μΑ
Gate-Body Leakage Current	I _{GSS}	$V_{GS}=\pm20V, V_{DS}=0V$			±100	nA
ON CHARACTERISTICS (Note 3)	<u> </u>					
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	1.08	1.65	2.38	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =10A		5.5	8.0	mΩ
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =6A		7.5	14	mΩ
DYNAMIC CHARACTERISTICS (Note	e4)					
Input Capacitance	C _{Iss}	V 45V/V 0V		1200		PF
Output Capacitance	C _{oss}	$V_{DS}=15V, V_{GS}=0V,$		200		PF
Reverse Transfer Capacitance	C _{rss}	- F=1.0MHz		130		PF
SWITCHING CHARACTERISTICS (N	ote 4)		•	•		
Delay Time	t _{d(on)}			3		nS
Turn-on Rise Time	t _r	V_{DS} =15V, V_{DS} =15V, R_{GEN} =6 Ω R_{L} =1 Ω , ID =14A		80		nS
Turn-Off Delay Time	t _{d(off)}			30		nS
Turn-Off Fall Time	t _f			10		nS
Total Gate Charge	Q_g			26		nC
Gate-Source Charge	Q _{gs}	V_{DS} =15 V , I_{D} =20 A , V_{GS} =15 V		11		nC
Gate-Drain Charge	Q_{gd}	1		9		nC
DRAIN-SOURCE DIODE CHARACTE	RISTICS		•			
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =40A			1.2	V
Diode Forward Current (Note 2)	Is				40	Α
Reverse Recovery Time	trr	TJ = 25℃, IF =1A		78		ns
Reverse Recovery Charge	Qrr	di/dt = 100A/us (Note3)	51			nc

NOTES:

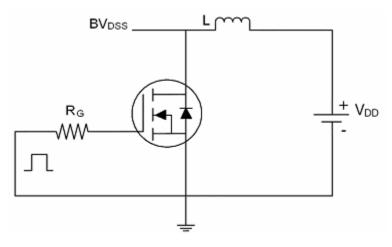
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on 1in² FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production testing
- 5.EAS condition Tj=25 ,VDD=15V,VG=10V,L=0.5mH,Rg=25

www.fnk-tech.com Page 2 V1.1

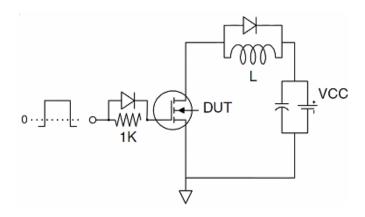


Test circuit

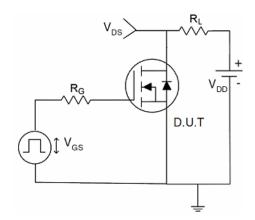
1) EAS test Circuits



2) Gate charge test Circuit



3) Switch Time Test Circuit



www.fnk-tech.com Page 3 V1.1



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

100

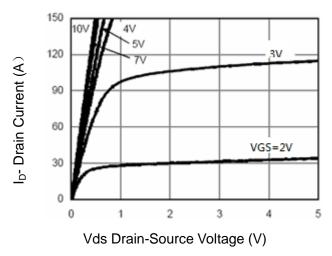
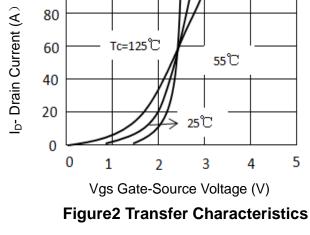
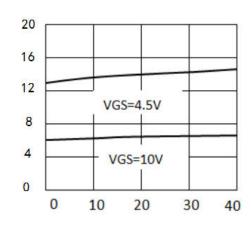


Figure 1 Output Characteristics





Rdson On-Resistance(Ω)

ID- Drain Current (A) Figure 3 Drain-Source On-Resistance

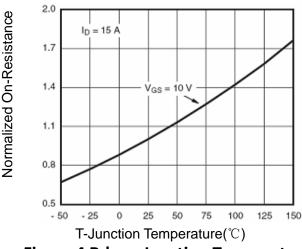


Figure 4 Rdson-Junction Temperature

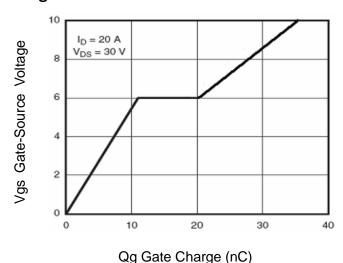
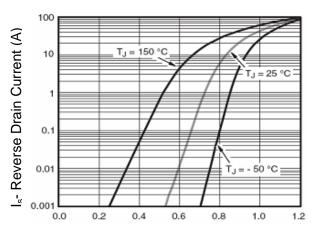


Figure 5 Gate Charge



Vsd Source-Drain Voltage (V)

Figure 6 Source- Drain Diode Forward

V1.1 www.fnk-tech.com Page 4



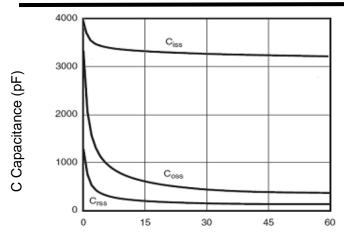


Figure 7 Capacitance vs Vds

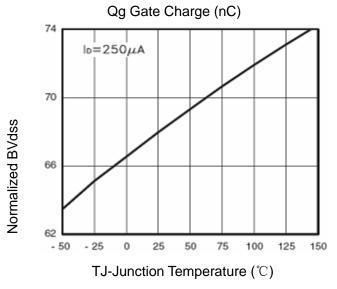


Figure 9 BVDSS vs JunctionTemperature

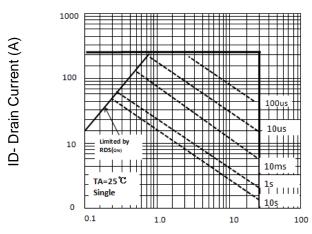


Figure 8 Safe Operation Area

Vds Drain-Source Voltage (V)

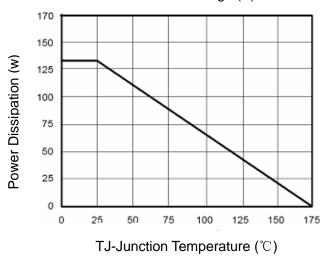


Figure 10 Power De-rating

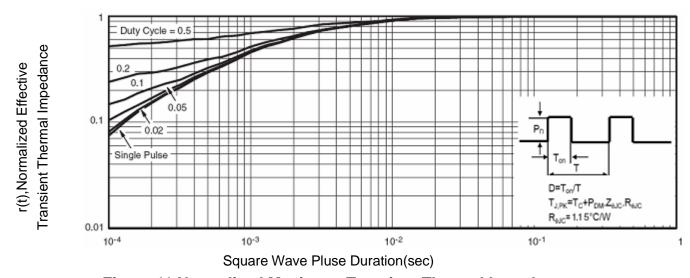
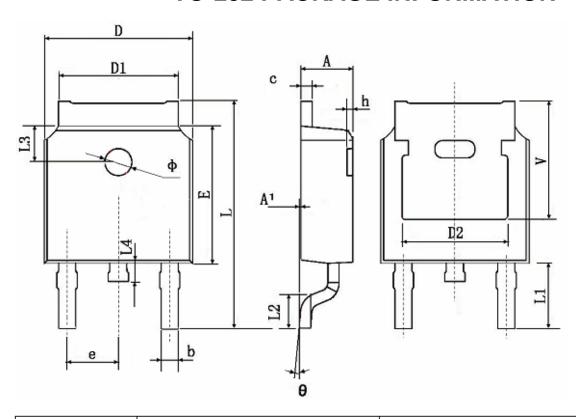


Figure 11 Normalized Maximum Transient Thermal Impedance

www.fnk-tech.com Page 5 V1.1



TO-252 PACKAGE INFORMATION



Symbol	Dimensions I	n Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	4.830	TYP.	0.190 TYP.		
E	6.000	6.200	0.236	0.244	
e	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900	TYP.	0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600	1.600 TYP.		TYP.	
L4	0.600	1.000	0.024	0.039	
Φ	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350 TYP.		0.211 TYP.		

www.fnk-tech.com Page 6 V1.1



ATTENTION:

- FNK reserves the right to make changes to the information herein for the improvement of the design and performance without further notice! Customers should obtain the latest relevant information before placing orders and should verify that such information is complete and current.
- FNK assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all FNK products described or contained herein.
- Specifications of any and all FNK products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- FNKstrives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- In the event that any or all FNK products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the FNK product that you intend to use.
- FNK will supply the best possible product for customers!

www.fnk-tech.com Page 7 V1.1